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FlipChip International Announces Official Opening of FABLAB, WLCSP & 3D Packaging Innovation Center

PHOENIX, ARIZONA March 17th, 2008—FlipChip International today announced the official opening of its FABLAB & Center of Innovation aimed at enabling future generations of Wafer Level Chip Scale Packaging (WLCSP) and 3D Packaging technologies. This new semiconductor development center is located at FCI's primary location in Phoenix, Arizona. The FABLAB concept supports ongoing strategic process and material development activities while, at the same time enabling advanced prototyping of leading edge and non-standard wafer level solutions in emerging product applications. Efforts are currently underway in a number of key areas including: finer pitch and improved mechanical robustness WLCSP technologies, fine pitch flip chip including Cu Pillar Bump, Integrated Passive on Chip, Embeddable Die Customization™, MEMS-WLCSPs, and 3D Wafer Level Packaging. Furthermore, this facility will ensure seamless production scale-up and technology transfer of these new technologies into FCI's affiliated wafer level manufacturing facilities either in Phoenix or at its expanding network of offshore joint ventures.

Bob Forcier, President and CEO of FlipChip International, stated, "This grand opening represents a milestone in FlipChip's five year Product Roadmap for its innovative Wafer Level Packaging Technology. This R&D Center will enable our customers rapid time-to-market prototypes with best in class technology. We are dedicated to developing cost-effective solutions such as our successful Spheron WLCSP, which can provide higher performance and more value for our customers."

Ted Tessier, Chief Technical Officer of FlipChip International, said, "For much of the past decade, FCI has been at the forefront of wafer bumping and WLCSP product and process engineering. I am truly excited by the potential of our FABLAB vision to become a primary innovation engine for the industry's move into 3D Wafer Level Packaging."

FlipChip International, LLC is a privately held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. FlipChip International, LLC is a subsidiary of RoseStreet Labs LLC, a supplier of products and services for the renewable energy, semiconductor and life science markets.

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